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ADVANCED ELECTRONIC SOLUTIONS

AVIATION SERVICES

COMMUNICATIONS AND CONNECTIVITY

MISSION SYSTEMS

GR740 - Next Generation Microprocessor (NGMP)

Cobham Gaisler

2015-06-01

Presenter: Jan Andersson

Final Presentation Days 2015
ESA/ESTEC

What is NGMP?

- NGMP: Next Generation Microprocessor
 - (Next Generation Multi Purpose Microprocessor)
- NGMP is an ESA activity developing a multi-processor system with higher performance than earlier generations of European space-microprocessors
- The NGMP is part of the ESA roadmap for standard microprocessor components
- The goal of this contract was specification of the architecture, architectural (VHDL) design, and verification by simulation and on FPGA. The goal of this work was to produce a verified gate-level netlist for a suitable technology. Contract was then extended to also include (almost all) work up to mask production.

Team

- Team (tech):
 - Cobham Gaisler (SE): Requirements, verification, synthesis, (FPGA) validation
 - M. Hjorth, M. Sjölander, N-J. Wessman, J. Gaisler, D. Hellström, M. Åberg, A. Larsson, D. Cederman, A. Gianarro, M. Isomäki, K. Glembo
 - EADS Astrium, now AD&S (FR, D): Requirements, specification
 - V. Lefftz, JF. Coldefy, H. Fischer, O. Notebaert
 - STMicroelectronics (FR, UK): Tech provider, Layout
 - R. Chevallier, R. Forsyth
 - ESA: Roland Weigand (TO), Luca Fossati
- Functional prototype development team: Cobham Gaisler (SE), Pender Electronic Design (CH), eASIC (US, RO)
- Input received from several parallel activities at ESA and CNES. As well as from internal R&D efforts at several companies

- To develop a microprocessor (NGMP) with higher performance than earlier European space-microprocessors
 - Establish NGMP specification, selection of suitable IP cores, design feasibility assessment, SEE mitigation assessment, considering also SW induced requirements to facilitate reuse of existing SW
 - Establish requirements for OS and SW development tools
 - NGMP design implementation in HDL and verification by simulation
 - Adaption of compilers, BSP for OS and development of drivers for the on-chip peripherals
 - NGMP verification and co-verification with OS and drivers on FPGA platform
 - Advanced synthesis on the target technology, baseline ST Space-DSM
 - Preliminary validation of the applied SEE mitigation by analysis simulation and fault injection

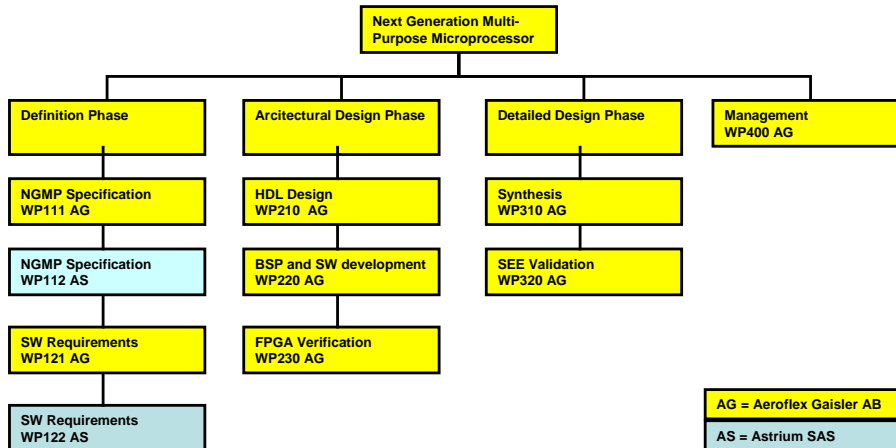
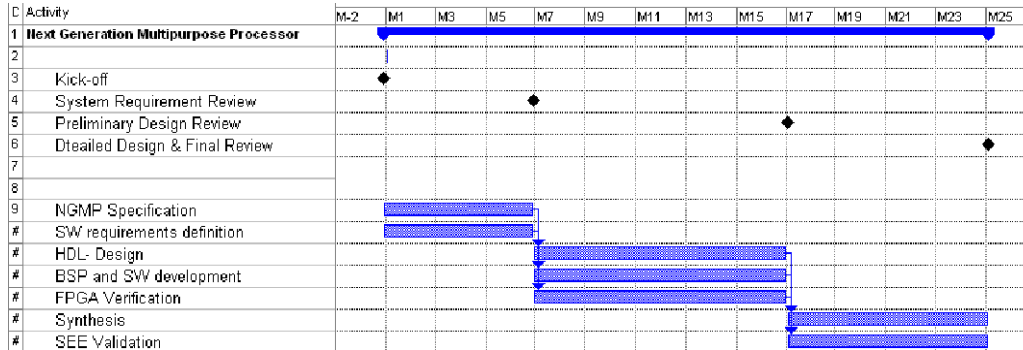
NGMP CCN: Feature extensions, detailed design and layout

- Extension of phase 1 to also include layout work
 - Extend Level-2 cache to allow handling cache hits while performing miss processing
 - Final synthesis, gate-level simulations, layout verification
 - Back-end work

- Specification
- Architectural design
 - Software/tool support (debugger, simulator, toolchains)
 - Benchmarks / trade-offs
 - Evaluation boards (functional prototype, FPGA prototypes)
- Detailed design, verification
- Layout and layout verification
- (Package design)

Schedule and work packages

Phase 1 + 0.5

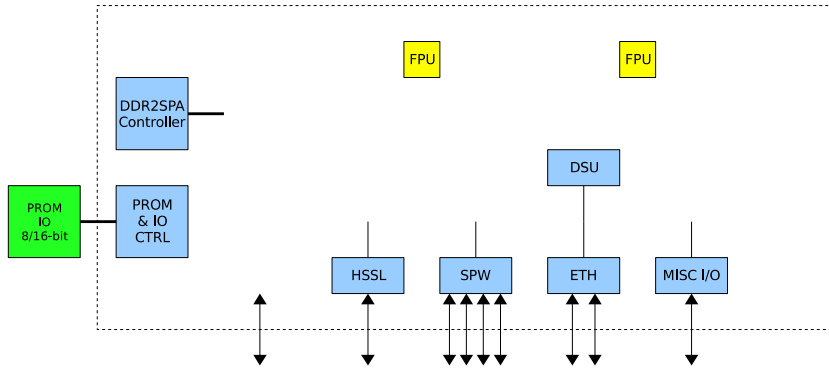


- Milestone completion:
 - T0: 1st of Aug 2009
 - SRR: Feb 2010
 - PDR: Dec 2010
 - (FP development)
 - pDDR: June 2014
 - Planned: Aug 2011
 - T0_{CCN} 15th July 2014
 - DDR/pCDR: Dec 2014
 - Planned: Oct 2014
 - pCDR/FR: April 2015
 - Planned: Nov 2014

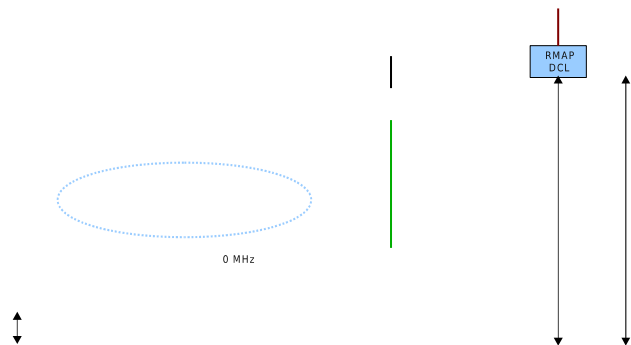
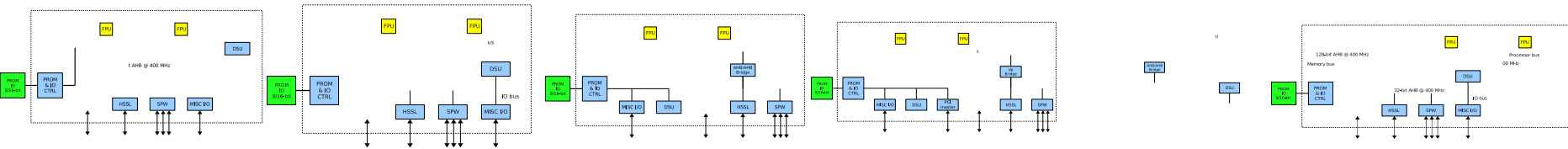
- CCN WP510: Feature extension
- CCN WP610: Detailed design and pre-layout verification
- CCN WP710: Layout generation and verification

Evolution of design

Proposal -> Specification, SRR



- Proposal, December 2008

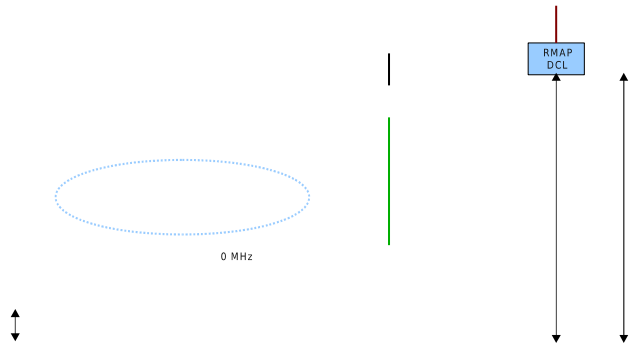


- Specification, February 2010

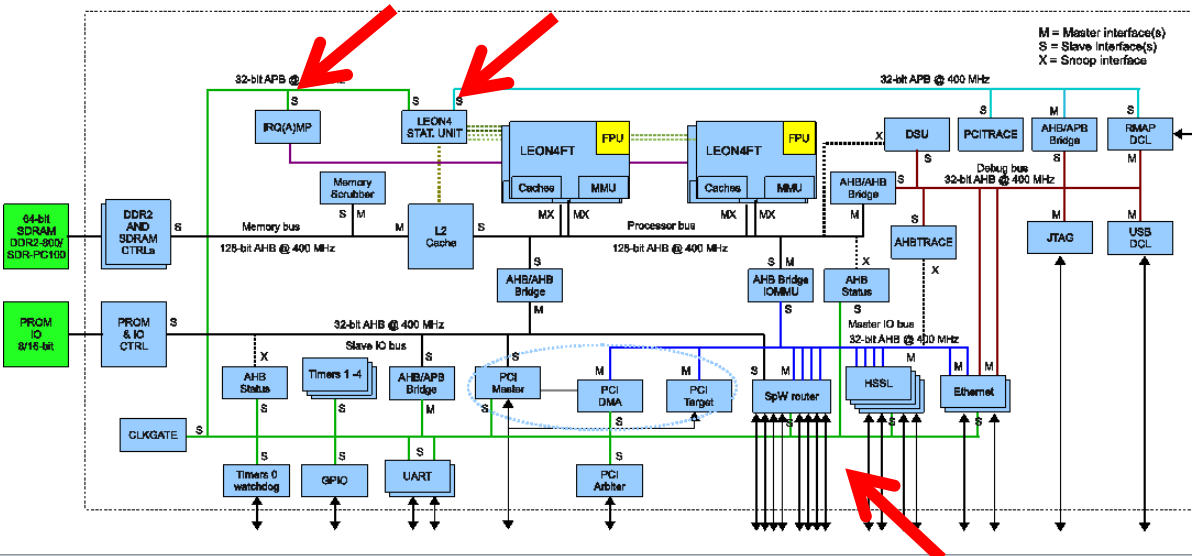
Evolution of design

SRR to PDR

- SRR, February 2010

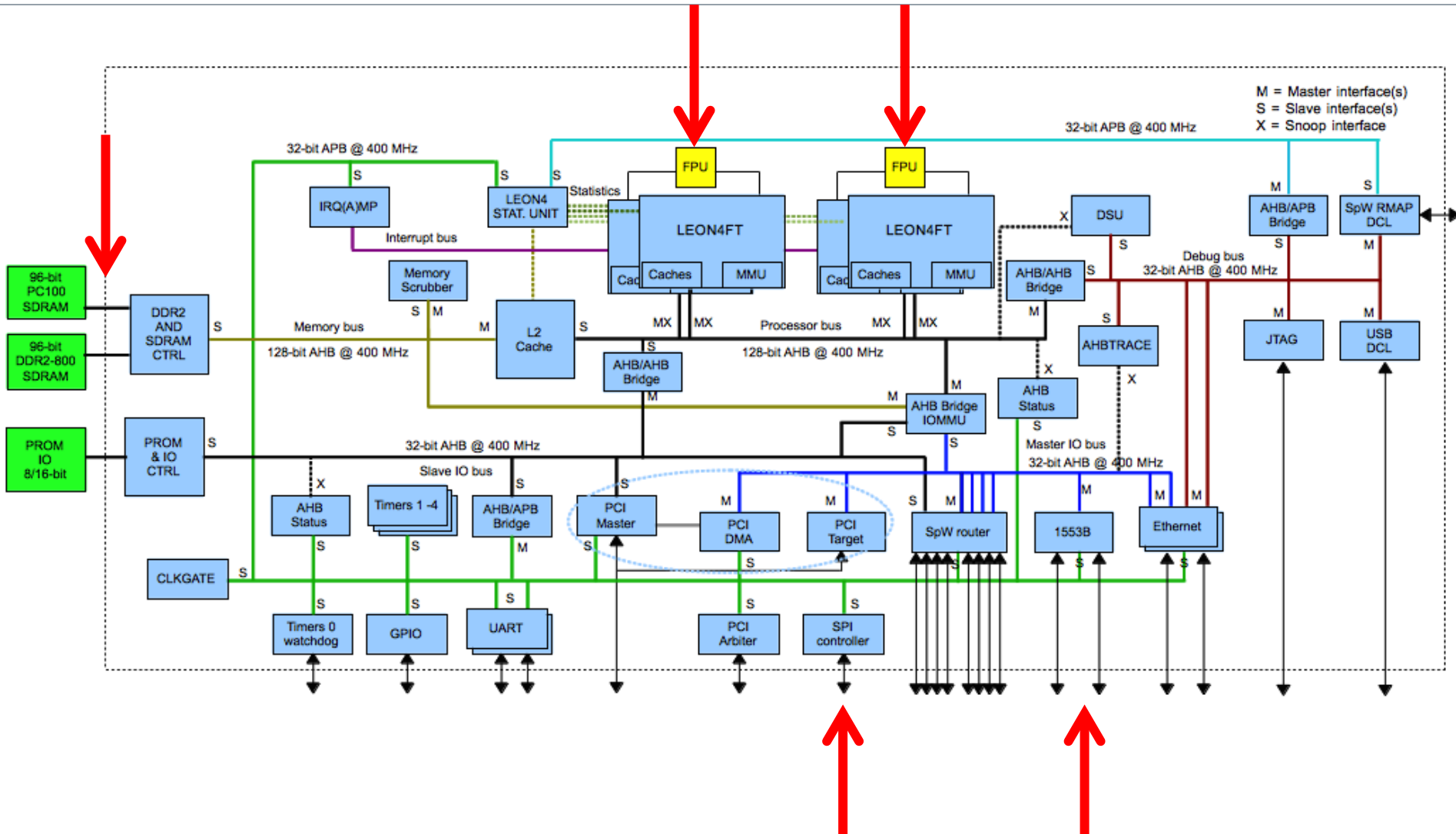


- PDR, December 2010



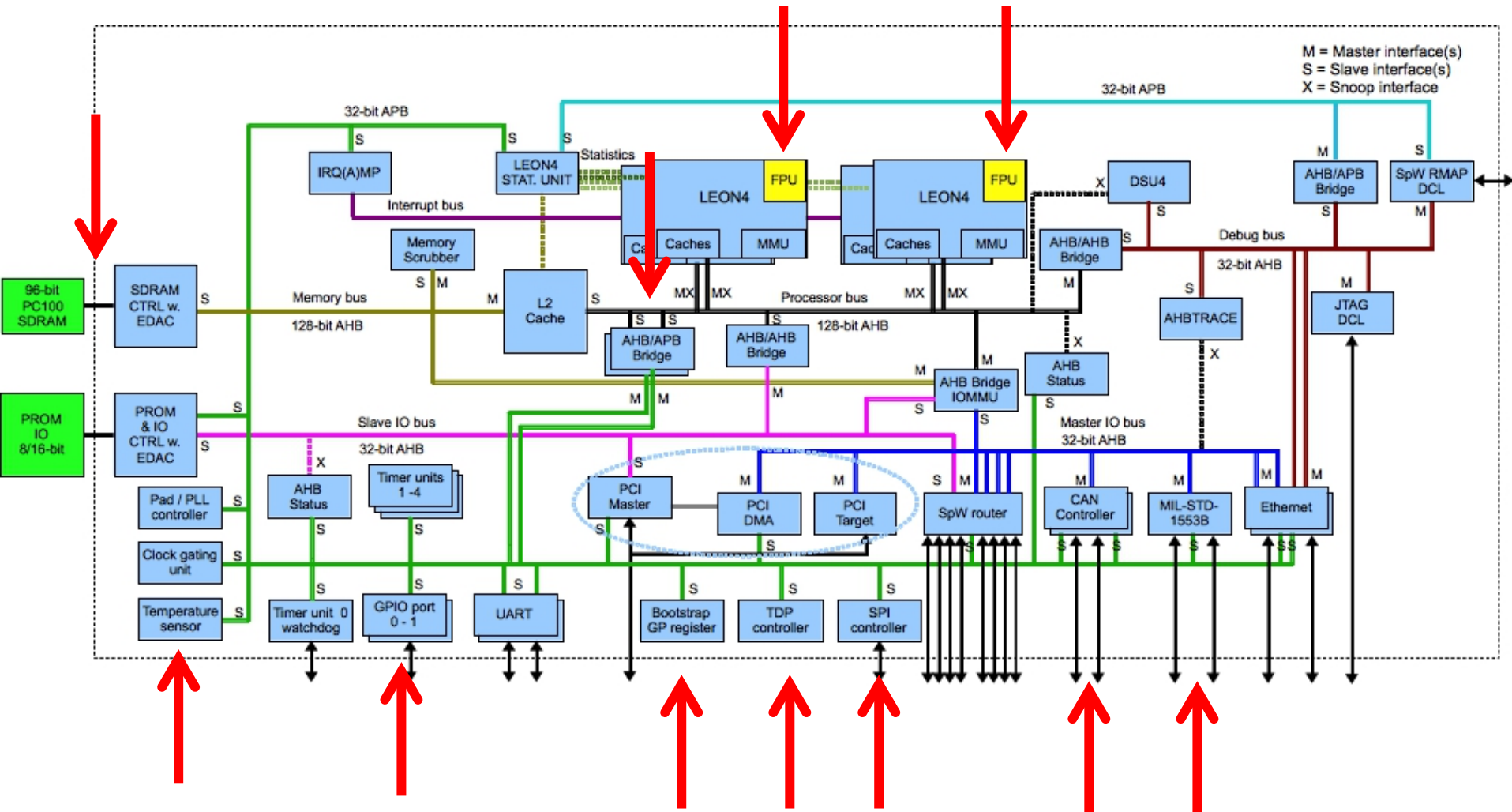
Evolution of Design

Functional prototype implementation



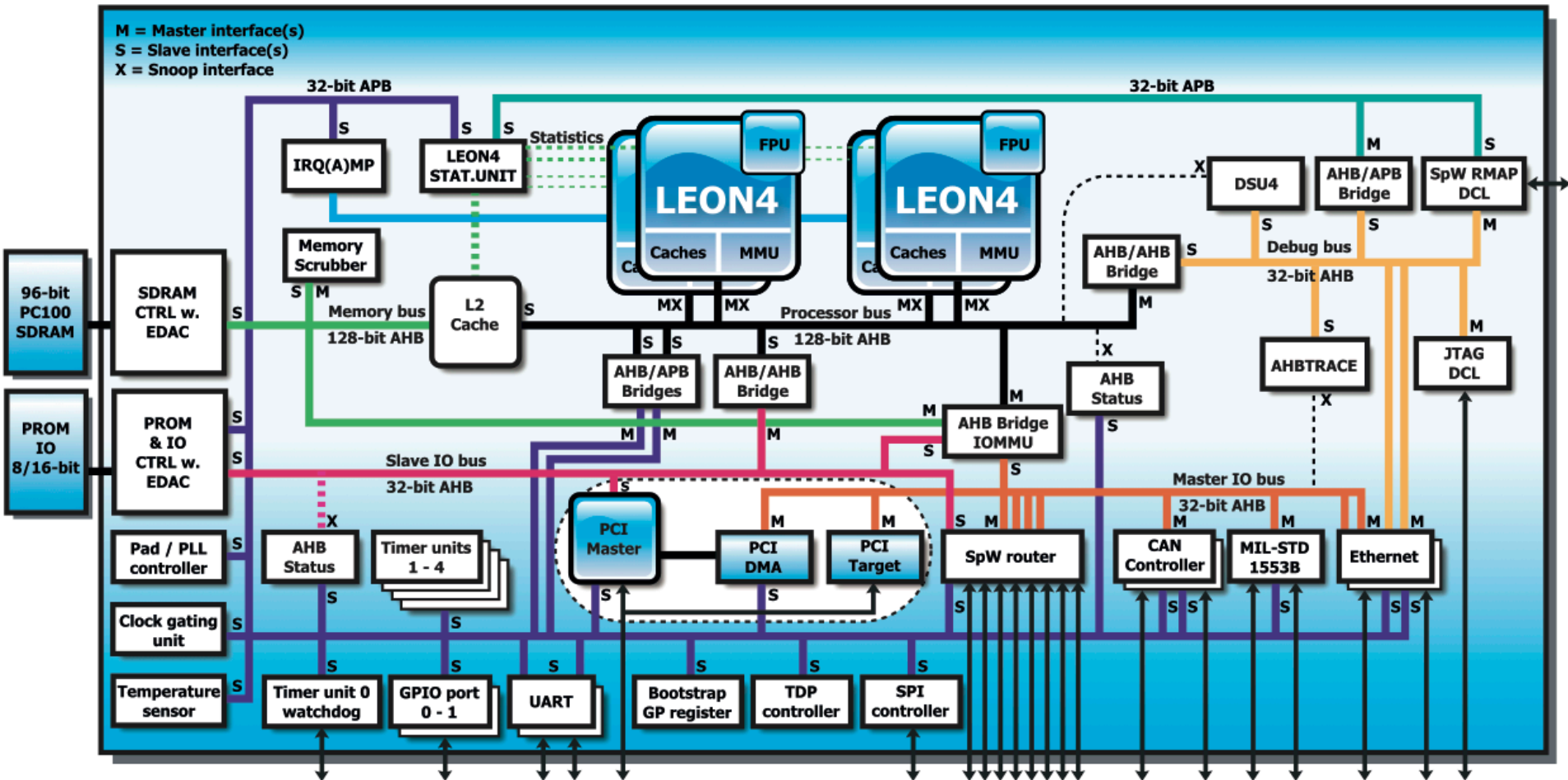
Evolution of Design

NGMP EM – GR740



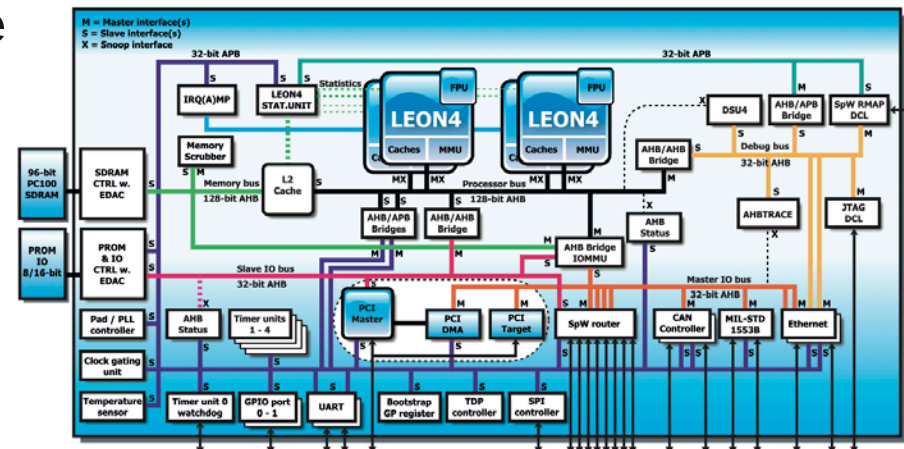
Description of design

GR740



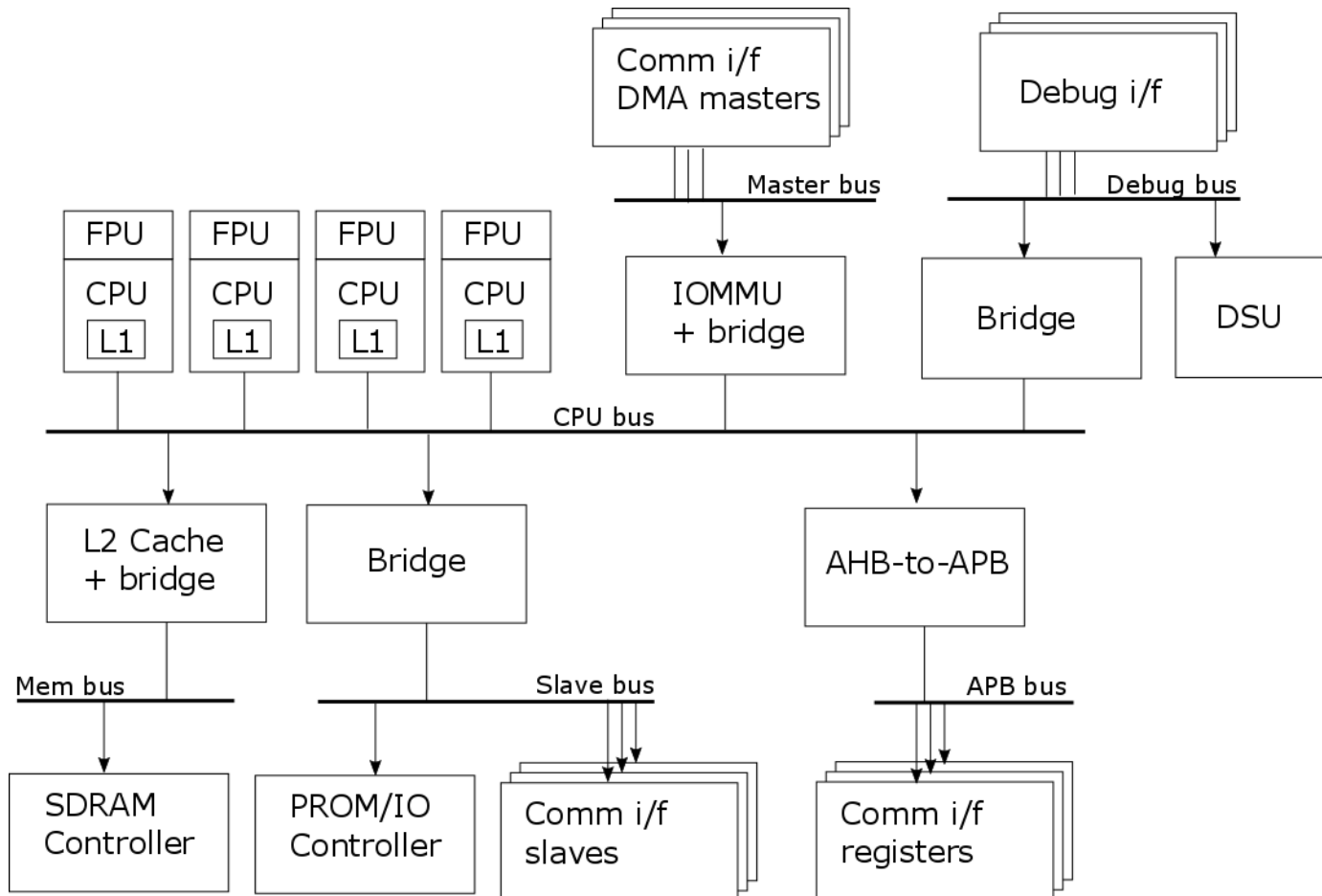
- System-on-chip

- 4 x LEON4 fault tolerant CPU:s with L1 cache, MMU and FPU
- 2 MiB Level-2 cache
- 96/48-bit SDRAM controller with EDAC and scrubber
- 8/16-bit PROM/IO controller with EDAC
- 5 x Timer, 5 x IRQ controller
- IOMMU for peripheral DMA
- On-chip AHB bus infrastructure
- PLLs for clock generation
- Communication interfaces



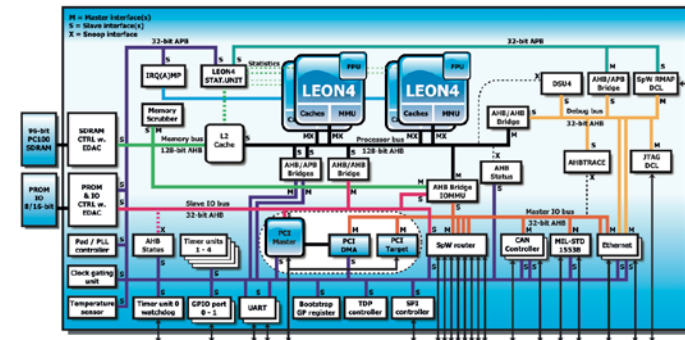
Simplified block diagram

- Architecture block diagram (simplified)



- Interfaces

- 8-port Spacewire router with on-chip LVDS
- 2 x 1Gbit/100Mbit Ethernet MAC (MII/GMII)
- PCI master/target with DMA, 33/66 MHz
- Dual-redundant CAN
- MIL-STD-1553B interface (bus A/B)
- 2 x UART
- 16 x GPIO



- Debug interfaces (for GRMON connection)

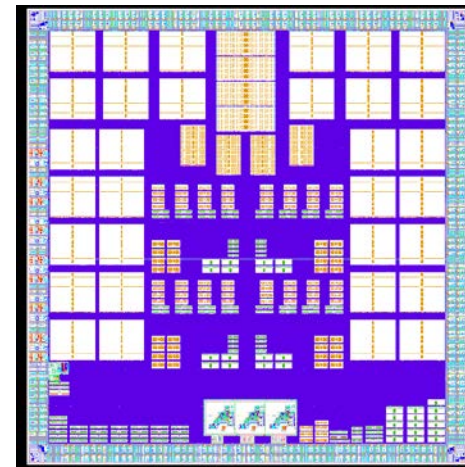
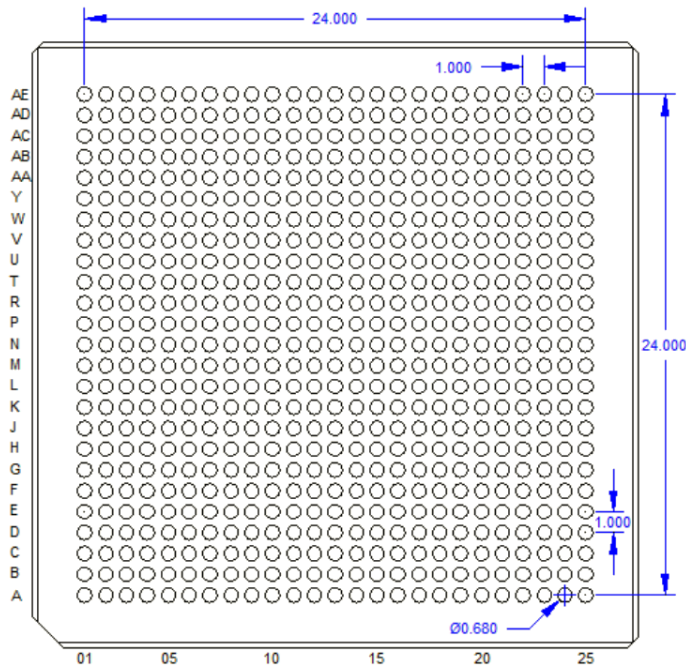
- Ethernet EDCL (using either of the two MACs above)
- JTAG
- Spacewire RMAP (separate GRSPW2 for debug only)

Interface restrictions

- Some functions have been multiplexed onto the same pins to fit into package
- Either PCI or second Ethernet (not both) can be enabled only when SDRAM is in 48-bit mode.
 - Configured “hard” via bootstrap signals.
- CAN, 1553, UART, SpwDebug are shared with PROM top address bits and data bits unused in 8-bit mode.
 - Power-on state of muxing configured via bootstrap signal. Can then be reconfigured by software while running.
 - Configurable pin-by-pin between PROM or peripheral function.
 - Pins that are not used for either function can be used as additional GPIO.

Package

- Targeted package for prototype is CLGA625
 - Hermetic ceramic package
 - Wire-bond connection to ASIC
 - Approx 30 mm x 30 mm



- Design is radiation hardened using multiple techniques
 - C65SPACE process and cell libraries designed and characterized for radiation hardness
 - Memories SEU-protected at design level using EDAC schemes.
 - Processor register files using block-TMR scheme

The NGMP shall be fault tolerant against SEU and SET effects tolerating a maximum rate of 10⁻⁵ uncorrectable errors per NGMP device per day corresponding to an MTBF of 274 years in geostationary orbit (conditions: solar minimum, Z=1 – 92, Al shielding of 1 g/cm²).
- Hardness to be validated by radiation testing (heavy ion, TID) on prototype.
- Baseline is to re-use exact same ASIC design and package for future flight models.

Clock frequencies

- Maximum clock frequencies obtained from post-layout STA:
 - System clock (CPU:s, L2Cache, on-chip buses): 250 MHz
 - 4 CPUs x 250 MHz x 1.7 DMIPS/MHz = 1700 DMIPS
 - Spacewire phy: 400 MHz
 - At least 300 Mbit/s data rate in point-to-point scenario (between two GR740:s) expected, limited by D/S skew. To be further characterized when silicon available.
 - SDRAM: 75 MHz expected (pad speed limited)
 - To be further characterized on silicon.
 - Maximum internal frequency 100 MHz.
 - Level-2 cache reduces impact of this limitation
- Timing valid for T_{junction} from -40 to +125°C
- Also 20 years of aging accounted for
- In room temperature likely to be faster than this.

Improvements: Multi-core aspects

SMP and AMP support

- Designed for both SMP and AMP/hybrid operation
 - Peripheral addresses aligned on 4KiB to allow MMU/IOMMU access control
 - Ability to use separate IRQ controller and timer for each CPU
 - IRQ remapping support
- Use cases
 - SMP, one OS (VxWorks, RTEMS-SMP, Linux) running on multiple cores with shared memory space
 - AMP, different single-core OS on each CPU with separate memory, (possibly also with some shared memory area)
 - Virtualized multi-core system with N isolated virtual CPU:s under hypervisor (XtratuM, PikeOS)
 - Hybrid of above approaches
 - ...and traditional single CPU core usage is still supported of course

Improvements: Various

Non-exhaustive list

- Performance
 - Additional processors
 - Level-2 cache
 - Wide buses
- Debugging
 - Dedicated debug bus non-intrusive debugging
 - Higher speed on debug interfaces
 - Performance counters
 - Instruction trace filters, Bus trace filters
 - Data area monitoring
 - PCI trace buffer
 - New features for instrumentation
- Interrupt timestamping – both in timer units and in interrupt controller
- Time synchronization
- Partitioning/Duplication: AMP and SMP
- Interrupt remapping
- Hardware memory scrubber for external RAM
- Async system (AMBA) and SDRAM clock
- Gigabit Ethernet
- IOMMU
- "Soft" watchdogs via NMI
- Level-2 cache
 - Protection of address ranges
 - Configurable between write-through and copy back
 - Optional use of hit-under-miss
 - Can be placed in "shallow queue" mode
 - Can be bypassed by IO DMA
- Processor internals
 - Wider datapaths
 - Up counter
 - Soft L1 replacement policy
 - Partial WRPSR
 - Branch prediction extensions
- GPIO interrupt flag register and multi-core-safe GPIO port register interface
- Pin-sharing control
- Reprogrammable PLLs
- Programmability of IOs
- Temperature sensor
- Programmable memory controller timing
- ... and recent version of all Cobham Gaisler IP

Improvements: Level-2 cache

Level-2 cache performance impact

- Reduced memory traffic
 - Level 2 cache has write-back policy so all CPU writes that hit in L1 or L2 do not have to go through to memory
 - DMA masters can also be served by L2
- Non-blocking L2 cache using SPLIT protocol
 - New feature for L2 cache in GR740!
 - CPU waiting on an L2 cache miss does not block remaining CPU:s from being served.
 - Reduce execution time interference between processors.
 - Less impact of external memory latency on overall performance of system.
 - Micro-benchmark shows >400% improvement over blocking L2 cache in worst case (one CPU always generating L2 misses, other CPUs never generating L2 misses)

- If 2 MiB RAM memory or less is needed, the chip can be used without any RAM connected at all!
 - Reduce part count for example when we are only interested in using the GR740 as a (very flexible) IO-to-IO bridge chip.
 - All Level-2 cache ways are locked down and tags set to map 1:1 to the lowest 2 MiB of RAM.
- Nominal boot method on GR740 is to boot up from 8-bit parallel PROM (NOR flash or MRAM)
 - Alternatively can be used without any PROM and instead booted up remotely via Spacewire RMAP, Ethernet EDCL protocol, or PCI.
 - Master node can boot up PROM-less slave nodes this way.
 - Upload software to RAM
 - Configure start address of CPU(s)
 - Start execution

- GR740 has been designed to allow time stamping of events and synchronization between CPU:s and interfaces
 - CPU cycle counter
 - Interrupts from any IP in system
 - Spacewire time codes
 - 1553 sync mode commands
- Can also be configured to toggle GPIO output when above events occur without software in the loop.

- Software for functional verification:
 - Bare-metal (multi-core extensions planned)
 - RTEMS (AMP, RTEMS-SMP from Gaisler in 4.11)
 - VxWorks 6.7 (Supports SMP)
 - Linux 2.6+ (Supports SMP)
 - eCos (Supports SMP, feedback welcome)
- Difference compared to GR712/UT*/LEON3FT*: Memory map + later versions of peripherals.
- GRMON2 debug monitor extended
- NGMP ISS based on GRSIM

- Specification
 - Trade-off for a general purpose microprocessor.
 - Multi-core aspects. Issues poorly understood.
- Increased verification and software effort due to refresh of RTL after activity was put on hold
- Creating a representative (timing accurate) simulator for GR740 based on existing simulator framework
- Trade-off between radiation hardening strategies
- Performance (timing) optimisations
- Disconnect between target technology development and needs/requirements on microprocessor device.
- Hit-under-miss-processing extension to Level-2 cache
- GLS: Several Mbit of memory, signal init (6h on core i7, later improved), default timing checks in sim lib introduced 'X'es

- Toolflow

- FE: DC+DFT Compiler, Formality, TetraMax, Questa/RivieraPRO, Avery Design SimXact
- BE: Standard ST flow

- Timing (worst-case, TBC)

System clock: 250 MHz SpaceWire clock: 400 MHz

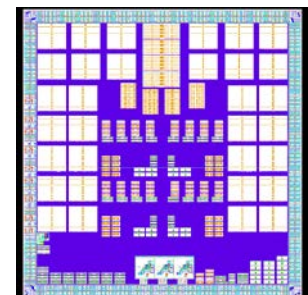
SDRAM clock: 75 MHz Ethernet GTX clock: 125 MHz

PCI clock: ~50 MHz (limited by IO timing)

- Power estimate (worse than worse-case): ████████████████████

- Design complexity:

- 15(+) clock domains
- SRAM bits: 25281728 (25.3 Mbit, 3 MiB), 268 instances
- Hard FFs: 130k Soft FFs: 93k Comb+ICG: 773k
- Buf/inv: 157k PLLs: 3 Pads: 152



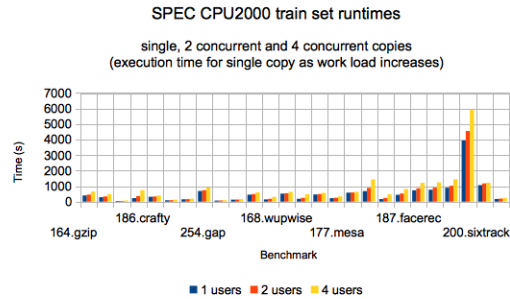
- LEON4 datasheet performance: 1.7 DMIPS/MHz, 2.1 CoreMark/MHz
- Results from technical note, released December 2010

Benchmark	AT697	UT699	GR712RC	NGMP
164.gzip	1	0.94	1.1	1.31
176.gcc	1	0.79	0.97	1.3
256.bzip2	1	0.93	1.06	1.33
AOCS	1	1.2	1.52	1.79
Basicmath	1	1.3	1.46	1.62
Coremark, 1 thread	1	0.89	1.09	1.21
Coremark, 4 threads	1	0.89	2.05	4.59
Drystone	1	0.94	1.05	1.39
Drystone, 4 instances	1	0.94	1.61	4.81
Linpac	1	1.2	1.26	1.71
Whetstone	1	1.94	2	2.22
Whetstone, 4 instances	1	1.94	3.7	8.68

Table 2: Performance comparison

Benchmark Results: Multi-Core

(Slide from 2012)



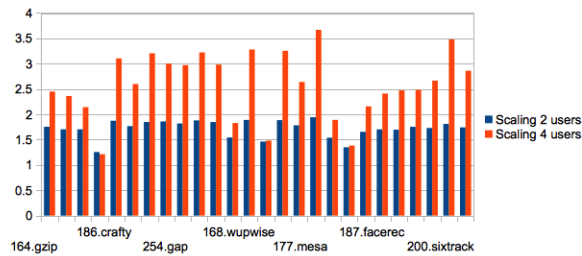
(Pessimistic) Average of scaling measurements:

Activating one additional core gives speed-up of 1.6 (range 1.3 – 1.94)

Activating three additional cores gives speed-up of 2.4 (range 1.2 - 3).

... in tests where workload is multiplied with number of cores!

Test is pessimistic as all (sequences) of accesses to shared resources will occur simultaneously.



Benchmark	Two parallel instances			
	System A (ideal speedup)	System B	System C WS	System C SPLIT
164.gzip	1.25	1.11	1.08	1.06
175.vpr	1.25	1.08	1.04	1.02
176.gcc	1.25	1.12	1.09	1.08
181.mcf	1.25	1.05	1.02	0.99
186.crafty	1.25	1.03	0.97	0.96
197.parser	1.25	1.17	1.16	1.12
252.eon	1.25	1.09	1.04	1.04
253.perlbmk	1.25	1.07	1.02	1.01
254.gap	1.25	1.16	1.12	1.11
255.vortex	1.25	1.12	1.09	1.08
256.tzip2	1.25	1.18	1.17	1.13
300.twolf	1.25	1.12	1.10	1.06
168.wupwise	1.25	1.23	1.23	1.19
171.swim	1.25	1.10	1.09	1.04
172.mgrid	1.25	1.23	1.23	1.17
173.applu	1.25	1.22	1.22	1.18
177.mesa	1.25	1.24	1.24	1.23
178.galgel	1.25	1.10	1.09	1.06
179.art	1.25	1.19	1.18	1.03
183.equake	1.25	1.19	1.18	1.09
187.facerec	1.25	1.20	1.20	1.18
188.ammip	1.25	1.17	1.16	1.10
189.lucas	1.25	1.22	1.22	1.19
191.fma3d	1.25	1.12	1.09	1.08
200.sixtrack	1.25	1.22	1.21	1.20
301.apsi	1.25	1.19	1.18	1.15

Table 2: SPEC CPU2000 speedup

- Other benchmark efforts: Dedicated FPU vs. shared, LEON double clocking, IO traffic routing, ...

	No SPLIT, 128-bit		SPLIT, 128-bit		No SPLIT, 32-bit		SPLIT, 32-bit	
Total	149194338		97371011		388420963		85449832	
CPU0	2579067	1.73%	2579067	2.65%	2579067	0.66%	2579067	3.02%
CPU1	2578234	1.73%	2578311	2.65%	2578184	0.66%	2579281	3.02%
CPU2	2578256	1.73%	2578326	2.65%	2578206	0.66%	2578169	3.02%
CPU3	2639689	1.77%	1365166	1.40%	2639641	0.68%	595467	0.70%
AHB utilization:	6.95%		9.35%		2.67%		9.75%	
"Fair" speed-up:			1.34				3.65	

SPEC Benchmarks

- Impossible to exactly prototype GR740 system on FPGA for SPEC benchmarks
 - Not enough on-chip RAM on FPGA to implement 2 MiB L2-cache
 - FPGA boards using SDRAM do not have enough RAM to run SPEC
 - Different AHB/memory clock ratio when using DDR memory
 - Only the training set can be run within reasonable time
- General conclusion looking at multiple benchmarking campaigns during development:
 - We expect 10-15% improvement/MHz in SPECint/fp compared earlier LEON3 components in single-CPU case
 - Speedup of 2.54 measured when running 4 separate, independent, copies in parallel on 4 cores compared to 4 copies in sequence on 1 core.
 - Less than the ideal of 4.0 because of contention for L2 cache, effectively size reduced to 1/4 for each benchmark instance.
 - Together with frequency increase (from ~100 to 250 MHz), this gives about 600% improvement in processing power on SPEC-type applications compared to UT699/GR712 in single-core
- To be benchmarked on the real silicon

Deliverables to ESA

- Architecture Exploration Report
- **NGMP Specification**
- Development Plan
- SEE Mitigation Plan
- Feasibility Report with Spreadsheet
- Software Requirements Specification
- Architecture Definition Report
- Verification Document
- Preliminary NGMP Data sheet
- Documentation of Changes/Configuration of OS, Compiler and the Drivers
- **Technical Note on NGMP Evaluation**
- Preliminary Radiation Report
- Technical Data Package
- **Abstract and Executive Summary**
- **FPGA board with FPGA database**
- **High-level simulation models**
- Architectural Design Database
- Software databases
- Test database
- Detailed Design Database
- Detailed Design Document
- Layout Design Document
- **Preliminary datasheet for ST65 Prototype Implementation**
- **Bitstream for FPGA board – representative of full NGMP**
- **Bitstream for FPGA board – representative of GR740**
- Final design database
- Detailed block diagram (addition)
- ST65 ASIC Design Description (addition)
- ST65 DFT Specification (addition)
- **GR740 Comparison Document (addition)**

Bold = Public (free/non-free)

- Requirements and feedback are valuable but difficult to obtain
- Release prototypes early
 - Go for SW development and porting of existing applications
 - Minimize number of different FPGA configurations
- Early trials: don't forget the IOs
- Keep space volumes in mind for DFT
- Try (harder) to align backend iterations with FE deliveries
- Watch out for swapping of RH elements (happened, checks were in place)

- To develop a microprocessor (NGMP) with higher performance than earlier European space-microprocessors: Check
- NGMP Phase 2 (GR740) started, PG estimated for Friday CW24
 - Radiation hardening measures, manufacturing on C65SPACE
 - Package "qualifiable"
 - Possibility to take EM silicon to FM
- NGMP/GR740 already in use through FPGA prototypes and functional prototype
- Multi-core aspects being evaluated – more work needed
- Technology advancement may provide gains for "small" design revision:
 - Memory interface, Communication interfaces, Computational perf.
- Extensions and improvements also available through IP

Thank you for listening!

Questions?

Latest status of GR740 development:

<http://www.gaisler.com/gr740>